



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D
<i>* : Required Field</i>			

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2016-01-27
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Authorized Representative *</b>	Rossana Bonaccorso	<b>Representative Title</b>	ADG MD CHAMPION
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**

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Legal Statement			
<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard

**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STPS340SY	BNZK*Z25SD1T	A	ZA41	2016-01-27
Amount		UoM	Unit type	ST ECOPACK Grade
250.00		mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		



Package Designator	Size	Nbr of instances	Shape	
SOJ	4.5X2.16X3.68	1	J bend	
Comment	Package: SMC CLIP (SOD 15 NEW)			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	false
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-20th June 2016				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	BNZK*Z25SD1T					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	1.143	mg	supplier	die	Silicon (Si)	7440-21-3		1.086	mg	950131	4344
				supplier	metallization	Aluminium (Al)	7429-90-5		0.007	mg	6124	28
				supplier	metallization	Titanium (Ti)	7440-32-6		0.001	mg	876	4
				supplier	metallization	Tungsten (W)	7440-33-7		0.002	mg	1750	8
				supplier	metallization	Nickel (Ni)	7440-02-0		0.005	mg	4374	20
				supplier	metallization	Gold (Au)	7440-57-5		0.005	mg	4374	20
				supplier	Passivation	Silicon Oxide	7631-86-9		0.007	mg	6124	28
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.001	mg	875	4
				supplier	back side metallization	Gold (Au)	7440-57-5		0.002	mg	1750	8
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.007	mg	6124	28
Leadframe & Clip	Copper and its alloy	89.949	mg	supplier	polymer die coating	Durimide	proprietary		0.020	mg	17498	80
				Supplier	alloy	Copper (Cu)	7440-50-8		89.905	mg	999511	359620
				Supplier	alloy	Zinc (Zn)	7440-66-6		0.004	mg	44	16
				Supplier	alloy	Iron (Fe)	7439-89-6		0.009	mg	100	36
				Supplier	alloy	Phosphorus (P)	7723-14-0		0.031	mg	345	124
Die Attach	Solder	4.283	mg	JIG - R	soft solder	Lead (Pb)	7439-92-1	7a-Lead in high met	3.962	mg	925053	15848
				Supplier	soft solder	Tin (Sn)	7440-31-5		0.214	mg	49965	856
				Supplier	soft solder	Silver (Ag)	7440-22-4		0.107	mg	24982	428
Encapsulation	Other organic material	152.483	mg	Supplier	Moulding Compound	Amorphous Silica	7631-86-9		93.624	mg	613996	374496
				Supplier	Moulding Compound	Quartz	14808-60-7		30.497	mg	200003	121988
				Supplier	Moulding Compound	epoxy resin	25068-38-6		18.298	mg	120000	73192
				Supplier	Moulding Compound	phenolic resin	29690-82-2		9.149	mg	60000	36596
				Supplier	Moulding Compound	Carbon black	1333-86-4		0.915	mg	6001	3660
Finishing	Solder	2.142	mg	supplier	connection coating	Tin (Sn)	7440-31-5		2.142	mg	1000000	8568